

### Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 2 X 0.75 (2.44X 0.9 EP)
Lead Count	10
Terminal Finish	NiPdAu

### Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

### Materials Declaration

#### Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	7.46E-03	83.25	832500	38.96		389577
Thermosets	Epoxy resin	Proprietary	4.86E-04	5.42	54200	2.54		25363
Thermosets	Phenol resin	Proprietary	3.09E-04	3.45	34500	1.61		16145
Other inorganic materials	Metal Hydroxide	Proprietary	4.86E-04	5.42	54200	2.54		25363
Others	Others	Proprietary	2.20E-04	2.46	24600	1.15		11512
Subtotal			8.96E-03	100.00	1000000	46.80		467960

#### Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	7.38 E-03	97.50	975000	38.56		385634
Copper & its alloys	Iron	7439-89-6	1.78 E-04	2.35	23500	0.93		9295
Copper & its alloys	Zinc	7440-66-6	9.09 E-06	0.12	1200	0.05		475
Copper & its alloys	Phosphorus	7723-14-0	2.27 E-06	0.03	300	0.01		119
Subtotal			7.57 E-03	100.00	1000000	39.55		395522

#### Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Nickel & its alloys	Nickel	7440-02-0	3.04 E-05	90.9	909091	0.16		1589
Precious metals	Palladium	7440-05-3	2.28 E-06	6.8	68182	0.01		119
Precious metals	Gold	7440-57-5	7.61 E-07	2.3	22727	0.00		40
Subtotal			3.35 E-05	100.00	1000000	0.17		1748

#### Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	5.76 E-06	99.99	1000000	0.03		301

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.47 E-03	100.0	1000000	12.88		128813

#### Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	8.34 E-05	77.00	770000	0.44		4355
Other organic materials	Acrylic resin	Proprietary	7.58 E-06	7.00	70000	0.04		396
Other organic materials	Acrylate	Proprietary	5.96 E-06	5.50	55000	0.03		311
Other organic materials	Polybutadiene derivative	Proprietary	4.87 E-06	4.50	45000	0.03		255
Thermoset	Epoxy resin	Proprietary	2.71 E-06	2.50	25000	0.01		141
Other organic materials	Butadiene Copolymer	Proprietary	1.62 E-06	1.50	15000	0.01		85
Others	Additive	Proprietary	1.62 E-06	1.50	15000	0.01		85
Others	Peroxide	Proprietary	5.41 E-07	0.50	5000	0.00		28
Subtotal			1.08 E-04	100.0	1000000	0.57		5656

<b>Package Totals</b>	<b>Weight (g)</b>	<b>1.91 E-02</b>	<b>Percentage (%)</b>	<b>100.00</b>	<b>PPM</b>	<b>1000000</b>
-----------------------	-------------------	------------------	-----------------------	---------------	------------	----------------

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary